

# X#-series SMT setup

# Flexible Inline AXI Platform

The X#-platform series is an inline automated X-ray system which covers a wide range of AXI applications. It is a flexible platform with very versatile fields of use depending on the application requirements. The SMT setup focuses on components and solder joints inspection on PCB's.

The Nordson Test & Inspection system solutions present a modular inspection concept. The platforms feature up to 4 advanced technologies in one system: Transmission X-ray imaging (2D) with patented Slice-Filter-Technique™ (SFT), Off-Axis technology (2.5D) and 3D SART (Simultaneous Algebraic Reconstruction Technique).

The X#-series platform is available in the following configurations:

- X2# Transmission (2D) + SFTTM
- X2.5# Transmission (2D) + SFTTM + Off-Axis (2.5D)
- X3# Transmission (2D) + SFTTM + Off-Axis (2.5D) + 3D SART

# Inspection & Process Software

- PC-Station with multi-core processor setup
- Windows 10 platform
- MIPS 5 Inspection Platform
  - Advanced algorithm library
  - CAD import for automatic inspection list generation
  - Simultaneous Algebraic Reconstruction Technique (3D SART; X3# only)
  - Automatic Tree Classification (ATC) for Auto-Rule-Generation
  - Offline programming for AXI program generation & simulation, tuning and defect reference catalogue
- Verification & Process control
  - MIPS Verify link with closed loop repair
  - MIPS Process with real time SPC

# X# series

# **Features and Benefits**

- Flexible AXI system for inline setups
- Microfocus X-ray tube (sealed tube / maintenance free)
- Multiple programmable motion system with servo drives
- Digital CMOS flatpanel detector
- Automatic grey-level and geometrical calibration
- Barcode scanner for serial number and product type selection
- Flexible setup for inline pass through or same-side in/out configuration
- Full product traceability via various Industry 4.0 MES-Interfaces
- IPC-CFX ready



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# **Applications**

#### Electronic components and solder joint

A unique advanced algorithm library is available for electronic applications, specifically for component and solder-joint inspection on PCB, hybrid or chip level assembly processes.

All standard SMD and THT/PTH components:

- BGA & dedicated off-axis head-in-pillow (HIP) algorithm
- Comprehensive QFN & gullwing algorithm
- Robust solder surface / heatsink void inspection
- Pin in paste barel fill measurement
- Discrete down to 1005 pitches

# **Specifications**

### Facilities

Dimensions	1775 mm (H) x 3100 mm (W) x 1760 mm (D)
Adjustable conveyor height (SMEMA)	890 – 980 mm
Weight	2.800 kg
Safe Operating Temperature	15° - 28 °C optimal 20° - 25° C
Power Consumption	max. 6 kW
Line Voltage	400 VAC, 50/60 Hz 3 phase, 16 A/
	208 VAC, 50/60 Hz 3 phase, 25 A
Air	5-7 Bar, < 2 l/min, filtered (30μ), dry, oil free

X-ray Image Chain	
X-ray Source (sealed tube)	
Energy	SMT Setup 130 kV/40 W
Grey resolution	14 Bit
CMOS Flatpanel Detector	75 μm pixel size (2,25 MPix) 50 μm pixel size (5 MPix)

Inspection features		
Max. sample size	510 mm x 400 mm	
Max. inspection area	480 mm x 400 mm	
Min. sample size	100 mm x 80 mm	
Sample thickness	0,8-10 mm	
Max. sample weight:	5 kg	
Max. sample weight	up to 40 deg	
Resolution	down to 3 µm / pix	

Inspection speed		
Transmission (X2, X2.5, X3)	up to 3-4 views /s	
Off-Axis (X2.5, X3)	up to 2-3 views /s	
3D SART (X3)	up to 3 s /FoV	

## Options

Barcodereader Auto BCR scanning station (x-y gantry)



#### For more information, speak with your Nordson representative or contact your Nordson regional office

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Installed axes	
x,y (linear drives)	sample table
z (linea drives)	magnification
u,v (optional)	detector movement
Conveyor setup	
pass through	single lane
in-out same side	dual lane
Assembly clearance	

Multiple axes programmable motion system

**Motion System** 

Assembly clearance	
Topside (incl. sample thickness)	100 mm
Bottom side (excl. sample thickness)	40 mm
Min. edge clearance for clamping	3 mm

Low-dose radiation filter



#### www.nordson.com/TestInspect

Specifications subject to change without notice